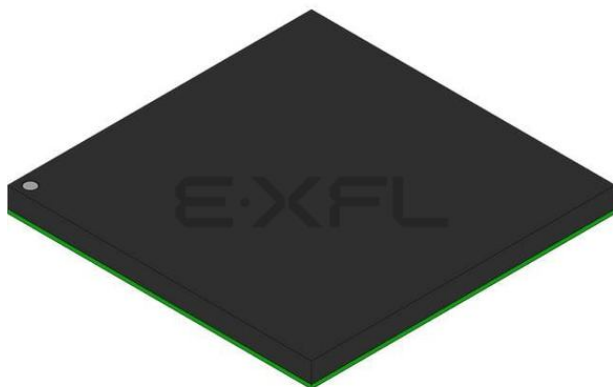




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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Active
Core Processor	PowerPC G2_LE
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	400MHz
Co-Processors/DSP	Communications; RISC CPM, Security; SEC
RAM Controllers	DRAM, SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (2)
SATA	-
USB	USB 2.0 (1)
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 105°C (TA)
Security Features	Cryptography, Random Number Generator
Package / Case	516-BBGA
Supplier Device Package	516-PBGA (27x27)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc8272cVRTIEA

1 Overview

This table shows the functionality supported by each SoC in the MPC8272 family.

Table 1. MPC8272 PowerQUICC II Family Functionality

Functionality	Package ¹	SoCs			
		MPC8272	MPC8248	MPC8271	MPC8247
		516 PBGA			
Serial communications controllers (SCCs)		3	3	3	3
QUICC multi-channel controller (QMC)		Yes	Yes	Yes	Yes
Fast communication controllers (FCCs)		2	2	2	2
I-Cache (Kbyte)		16	16	16	16
D-Cache (Kbyte)		16	16	16	16
Ethernet (10/100)		2	2	2	2
UTOPIA II Ports		1	0	1	0
Multi-channel controllers (MCCs)		0	0	0	0
PCI bridge		Yes	Yes	Yes	Yes
Transmission convergence (TC) layer		—	—	—	—
Inverse multiplexing for ATM (IMA)		—	—	—	—
Universal serial bus (USB) 2.0 full/low rate		1	1	1	1
Security engine (SEC)		Yes	Yes	—	—

¹ See [Table 2](#).

Devices in the MPC8272 family are available in two packages—the VR or ZQ package—as shown in . For package ordering information, see [Section 10, “Ordering Information.”](#)

Table 2. MPC8272 PowerQUICC II Device Packages

Code (Package)	VR (516 PBGA—Lead free)	ZQ (516 PBGA—Lead spheres)
Device	MPC8272VR	MPC8272ZQ
	MPC8248VR	MPC8248ZQ
	MPC8271VR	MPC8271ZQ
	MPC8247VR	MPC8247ZQ

This figure shows the block diagram of the SoC.

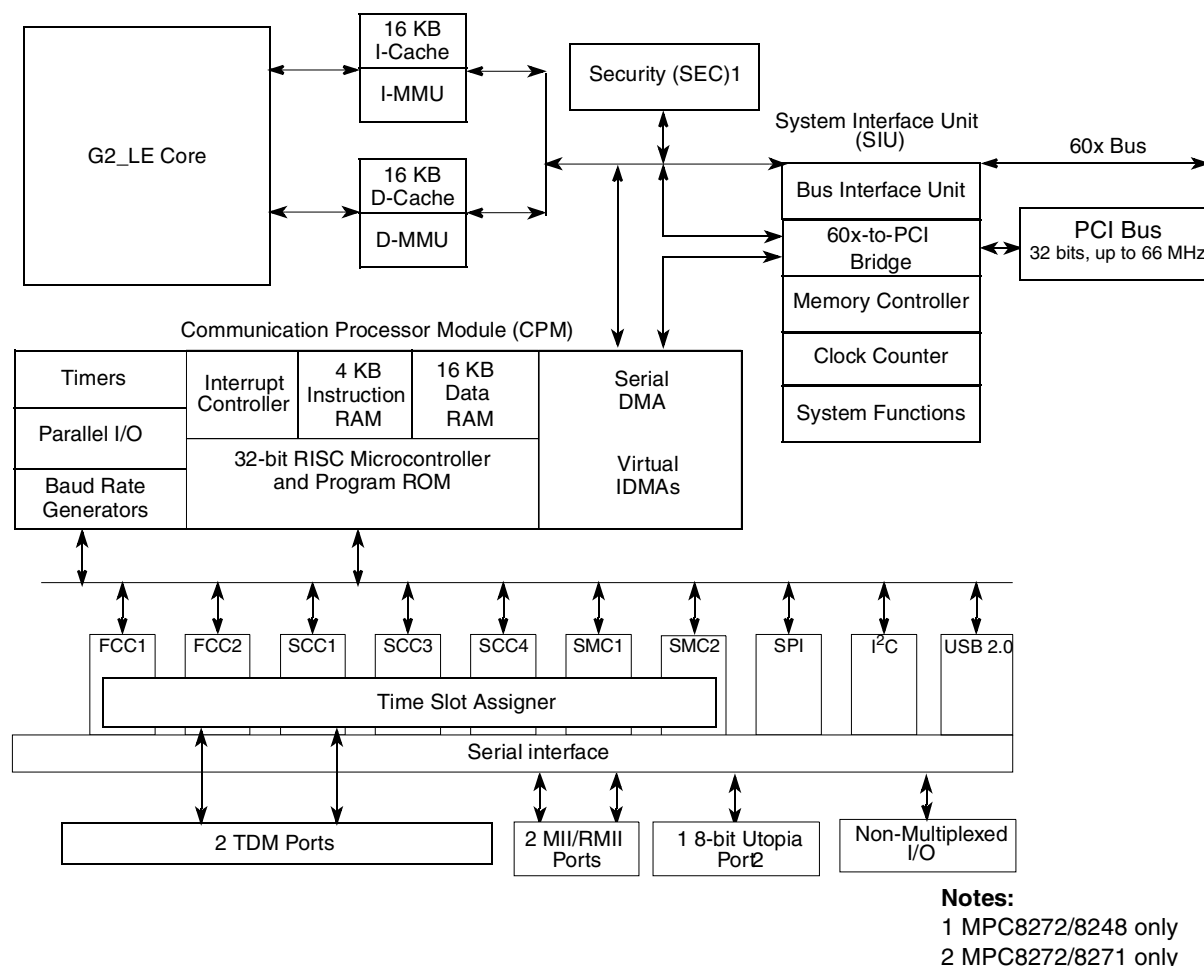


Figure 1. SoC Block Diagram

1.1 Features

The major features of the SoC are as follows:

- Dual-issue integer (G2_LE) core
 - A core version of the MPC603e microprocessor
 - System core microprocessor supporting frequencies of 266–400 MHz
 - Separate 16 KB data and instruction caches:
 - Four-way set associative
 - Physically addressed
 - LRU replacement algorithm
 - Power Architecture®-compliant memory management unit (MMU)
 - Common on-chip processor (COP) test interface
 - Supports bus snooping for cache coherency

This table lists recommended operational voltage conditions.

Table 4. Recommended Operating Conditions¹

Rating	Symbol	Value	Unit
Core supply voltage	VDD	1.425 – 575	V
PLL supply voltage	VCCSYN	1.425 – 575	V
I/O supply voltage	VDDH	3.135 – 3.465	V
Input voltage	VIN	GND (–0.3) – 3.465	V
Junction temperature (maximum)	T_j	105 ²	°C
Ambient temperature	T_A	0–70 ²	°C

¹ **Caution:** These are the recommended and tested operating conditions. Proper operation outside of these conditions is not guaranteed.

² Note that for extended temperature parts the range is $(-40)T_A - 105T_j$.

This SoC contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (either GND or V_{CC}).

This figure shows the undershoot and overshoot voltage of the 60x bus memory interface of the SoC. Note that in PCI mode the I/O interface is different.

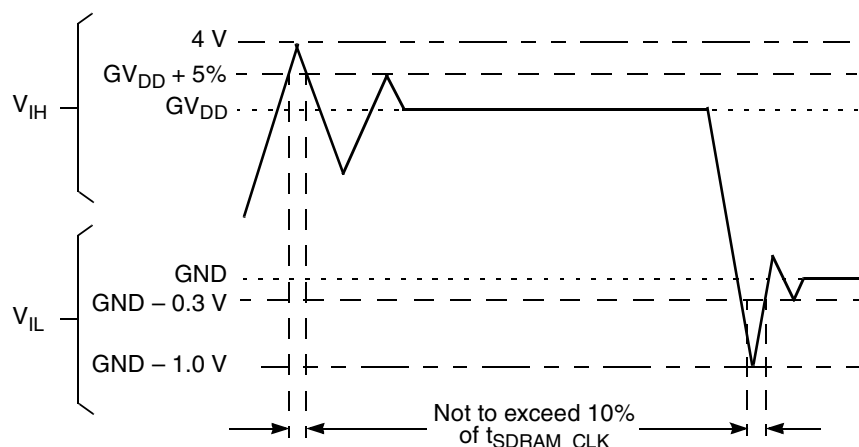


Figure 2. Overshoot/Undershoot Voltage

3 DC Electrical Characteristics

This table shows DC electrical characteristics.

Table 5. DC Electrical Characteristics¹

Characteristic	Symbol	Min	Max	Unit
Input high voltage—all inputs except TCK, $\overline{\text{TRST}}$ and $\overline{\text{PORESET}}$ ²	V_{IH}	2.0	3.465	V
Input low voltage ³	V_{IL}	GND	0.8	V
CLKIN input high voltage	V_{IHC}	2.4	3.465	V
CLKIN input low voltage	V_{ILC}	GND	0.4	V
Input leakage current, $V_{IN} = V_{DDH}$ ⁴	I_{IN}	—	10	μA
Hi-Z (off state) leakage current, $V_{IN} = V_{DDH}$ ²	I_{OZ}	—	10	μA
Signal low input current, $V_{IL} = 0.8 \text{ V}$	I_L	—	1	μA
Signal high input current, $V_{IH} = 2.0 \text{ V}$	I_H	—	1	μA
Output high voltage, $I_{OH} = -2 \text{ mA}$ except UTOPIA mode, and open drain pins In UTOPIA mode ⁵ (UTOPIA pins only): $I_{OH} = -8.0 \text{ mA}$ PA[8–31] PB[18–31] PC[0–1,4–29] PD[7–25, 29–31]	V_{OH}	2.4	—	V
In UTOPIA mode ⁵ (UTOPIA pins only): $I_{OL} = 8.0 \text{ mA}$ PA[8–31] PB[18–31] PC[0–1,4–29] PD[7–25, 29–31]	V_{OL}	—	0.5	V

Table 5. DC Electrical Characteristics¹ (continued)

Characteristic	Symbol	Min	Max	Unit
$I_{OL} = 5.3\text{mA}$ $\overline{CS}[0-5]$ $\overline{CS6}/\overline{BCTL1}/\overline{SMI}$ $\overline{CS7}/\overline{TLBSYNC}$ $\overline{BADDR27}/\overline{IRQ1}$ $\overline{BADDR28}/\overline{IRQ2}$ $\overline{ALE}/\overline{IRQ4}$ $\overline{BCTL0}$ $\overline{PWE}[0-7]/\overline{PSDDQM}[0-7]/\overline{PBS}[0-7]$ $\overline{PSDA10}/\overline{PGPL0}$ $\overline{PSDWE}/\overline{PGPL1}$ $\overline{POE}/\overline{PSDRAS}/\overline{PGPL2}$ $\overline{PSDCAS}/\overline{PGPL3}$ $\overline{PGTA}/\overline{PUPMWAIT}/\overline{PGPL4}$ $\overline{PSDAMUX}/\overline{PGPL5}$ $\overline{PCI_CFG0}(\overline{PCI_HOST_EN})$ $\overline{PCI_CFG1}(\overline{PCI_ARB_EN})$ $\overline{PCI_CFG2}(\overline{DLL_ENABLE})$ $\overline{MODCK1}/\overline{RSRV}/\overline{TC}(0)/\overline{BNKSEL}(0)$ $\overline{MODCK2}/\overline{CSE0}/\overline{TC}(1)/\overline{BNKSEL}(1)$ $\overline{MODCK3}/\overline{CSE1}/\overline{TC}(2)/\overline{BNKSEL}(2)$ $I_{OL} = 3.2\text{mA}$ $\overline{PCI_PAR}$ $\overline{PCI_FRAME}$ $\overline{PCI_TRDY}$ $\overline{PCI_IRDY}$ $\overline{PCI_STOP}$ $\overline{PCI_DEVSEL}$ $\overline{PCI_IDSEL}$ $\overline{PCI_PERR}$ $\overline{PCI_SERR}$ $\overline{PCI_REQ0}$ $\overline{PCI_REQ1}/\overline{CPI_HS_ES}$ $\overline{PCI_GNT0}$ $\overline{PCI_GNT1}/\overline{CPI_HS_LES}$ $\overline{PCI_GNT2}/\overline{CPI_HS_ENUM}$ $\overline{PCI_RST}$ $\overline{PCI_INTA}$ $\overline{PCI_REQ2}$ $\overline{DLLOUT}$ $\overline{PCI_AD}(0-31)$ $\overline{PCI_C}(0-3)/\overline{BE}(0-3)$ $\overline{PA}[8-31]$ $\overline{PB}[18-31]$ $\overline{PC}[0-1,4-29]$ $\overline{PD}[7-25,29-31]$ $\overline{TDO}$	V_{OL}	—	0.4	V

¹ The default configuration of the CPM pins ($\overline{PA}[8-31]$, $\overline{PB}[18-31]$, $\overline{PC}[0-1,4-29]$, $\overline{PD}[7-25,29-31]$) is input. To prevent excessive DC current, it is recommended either to pull unused pins to GND or VDDH, or to configure them as outputs.

² $\overline{TCK}$, $\overline{TRST}$ and $\overline{PORESET}$ have min $V_{IH} = 2.5\text{V}$.

³ V_{IL} for IIC interface does not match IIC standard, but does meet IIC standard for V_{OL} and should not cause any compatibility issue.

⁴ The leakage current is measured for nominal VDDH, VCCSYN, and VDD.

This table lists CPM input characteristics.

NOTE: Rise/Fall Time on CPM Input Pins

It is recommended that the rise/fall time on CPM input pins should not exceed 5 ns. This should be enforced especially on clock signals. Rise time refers to signal transitions from 10% to 90% of VCC; fall time refers to transitions from 90% to 10% of VCC.

Table 11. AC Characteristics for CPM Inputs¹

Spec Number		Characteristic	Value (ns)							
Setup	Hold		Setup				Hold			
			66 MHz	83 MHz	100 MHz	133 MHz	66 MHz	83 MHz	100 MHz	133 MHz
sp16a	sp17a	FCC inputs—internal clock (NMSI)	6	6	6	6	0	0	0	0
sp16b	sp17b	FCC inputs—external clock (NMSI)	2.5	2.5	2.5	2.5	2	2	2	2
sp18a	sp19a	SCC/SMC/SPI/I2C inputs—internal clock (NMSI)	6	6	6	6	0	0	0	0
sp18b	sp19b	SCC/SMC/SPI/I2C inputs—external clock (NMSI)	4	4	4	4	2	2	2	2
sp20	sp21	TDM inputs/SI	3	3	3	3	2.5	2.5	2.5	2.5
sp22	sp23	PIO/TIMER/IDMA inputs	8	8	8	8	0.5	0.5	0.5	0.5

¹ Input specifications are measured from the 50% level of the signal to the 50% level of the rising edge of CLKIN. Timings are measured at the pin.

NOTE

Although the specifications generally reference the rising edge of the clock, the following AC timing diagrams also apply when the falling edge is the active edge.

This figure shows the FCC internal clock.

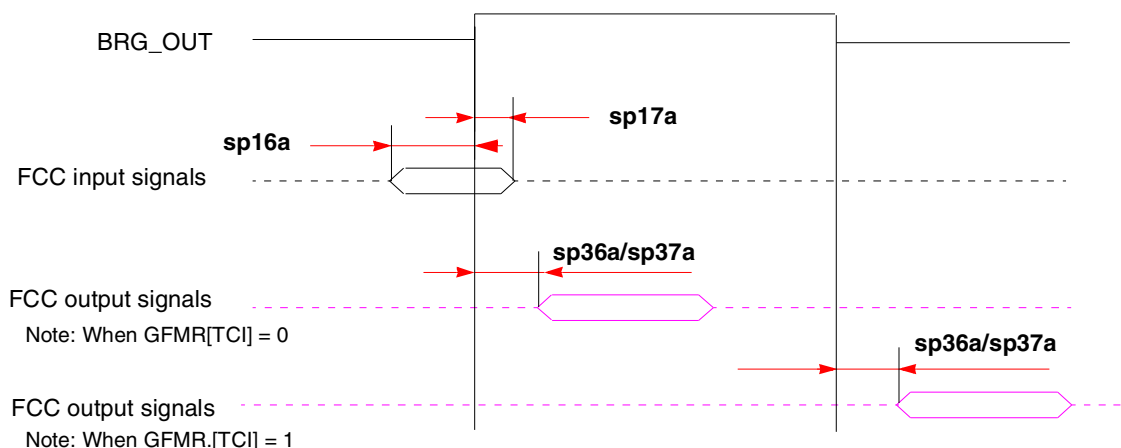


Figure 3. FCC Internal Clock Diagram

This figure shows the FCC external clock.

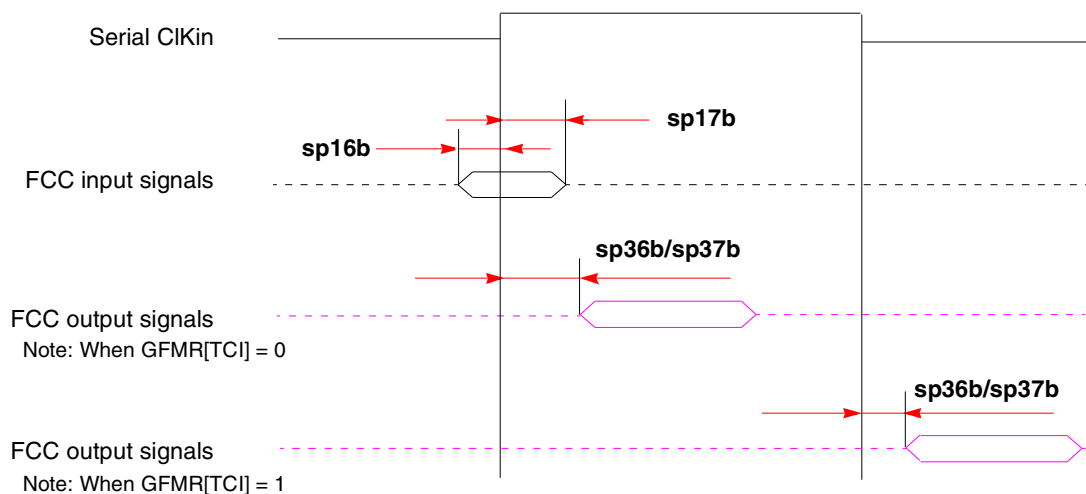
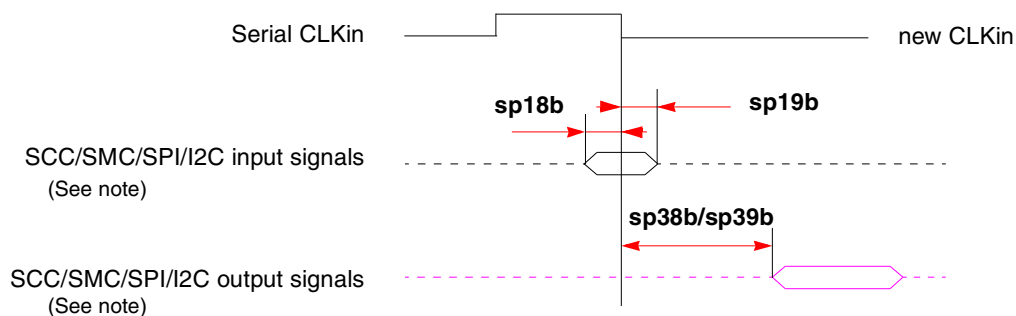


Figure 4. FCC External Clock Diagram

This figure shows the SCC/SMC/SPI/I²C external clock.



Note: There are four possible timing conditions for SPI:

1. Input sampled on the rising edge and output driven on the rising edge.
2. Input sampled on the rising edge and output driven on the falling edge.
3. Input sampled on the falling edge and output driven on the falling edge (shown).
4. Input sampled on the falling edge and output driven on the rising edge.

Note: There are two possible timing conditions for SCC/SMC/I²C:

1. Input sampled on the falling edge and output driven on the falling edge (shown).
2. Input sampled on the falling edge and output driven on the rising edge.

Figure 5. SCC/SMC/SPI/I²C External Clock Diagram

NOTE

The UPM machine outputs change on the internal tick determined by the memory controller programming; the AC specifications are relative to the internal tick. Note that SDRAM and GPCM machine outputs change on CLKIn's rising edge.

6.3 JTAG Timings

This table lists the JTAG timings.

Table 15. JTAG Timings¹

Parameter	Symbol ²	Min	Max	Unit	Notes
JTAG external clock frequency of operation	f_{JTG}	0	33.3	MHz	—
JTAG external clock cycle time	t_{JTG}	30	—	ns	—
JTAG external clock pulse width measured at 1.4V	t_{JTKHKL}	15	—	ns	—
JTAG external clock rise and fall times	t_{JTGR} and t_{JTGF}	0	5	ns	⁶
TRST assert time	t_{TRST}	25	—	ns	^{3, 6}
Input setup times	Boundary-scan data	t_{JTDVKH}	4	ns	^{4, 7}
	TMS, TDI	t_{JTIVKH}	4	ns	^{4, 7}
Input hold times	Boundary-scan data	t_{JTDXKH}	10	ns	^{4, 7}
	TMS, TDI	t_{JTIXKH}	10	ns	^{4, 7}
Output valid times	Boundary-scan data	t_{JTKLDV}	—	ns	^{5, 7}
	TDO	t_{JTKLOV}	10	ns	^{5, 7}
Output hold times	Boundary-scan data	t_{JTKLDX}	1	ns	^{5, 7}
	TDO	t_{JTKLOX}	1	ns	^{5, 7}
JTAG external clock to output high impedance	Boundary-scan data	t_{JTKLDZ}	1	ns	^{5, 6}
	TDO	t_{JTKLOZ}	1	ns	^{5, 6}

¹ All outputs are measured from the midpoint voltage of the falling/rising edge of t_{TCLK} to the midpoint of the signal in question. The output timings are measured at the pins. All output timings assume a purely resistive 50-Ω load. Time-of-flight delays must be added for trace lengths, vias, and connectors in the system.

² The symbols used for timing specifications herein follow the pattern of $t_{(first\ two\ letters\ of\ functional\ block)(signal)(state)\ (reference)(state)}$ for inputs and $t_{(first\ two\ letters\ of\ functional\ block)(reference)(state)(signal)(state)}$ for outputs. For example, t_{JTDVKH} symbolizes JTAG device timing (JT) with respect to the time data input signals (D) reaching the valid state (V) relative to the t_{JTG} clock reference (K) going to the high (H) state or setup time. Also, t_{JTDXKH} symbolizes JTAG timing (JT) with respect to the time data input signals (D) went invalid (X) relative to the t_{JTG} clock reference (K) going to the high (H) state. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

³ TRST is an asynchronous level sensitive signal. The setup time is for test purposes only.

⁴ Non-JTAG signal input timing with respect to t_{TCLK} .

⁵ Non-JTAG signal output timing with respect to t_{TCLK} .

⁶ Guaranteed by design.

⁷ Guaranteed by design and device characterization.

Table 17. Clock Configurations for PCI Host Mode (PCI_MODCK=0)^{1,2} (continued)

Mode ³	Bus Clock (MHz)		CPM Multiplication Factor ⁴	CPM Clock (MHz)		CPU Multiplication Factor ⁵	CPU Clock (MHz)		PCI Division Factor ⁶	PCI Clock (MHz)	
	Low	High		Low	High		Low	High		Low	High
0100_001	50.0	66.7	6	300.0	400.0	6	300.0	400.0	6	50.0	66.7
0100_010	50.0	66.7	6	300.0	400.0	7	350.0	466.6	6	50.0	66.7
0100_011	50.0	66.7	6	300.0	400.0	8	400.0	533.3	6	50.0	66.7
0101_000	60.0	66.7	2	120.0	133.3	2.5	150.0	166.7	2	60.0	66.7
0101_001	50.0	66.7	2	100.0	133.3	3	150.0	200.0	2	50.0	66.7
0101_010	50.0	66.7	2	100.0	133.3	3.5	175.0	233.3	2	50.0	66.7
0101_011	50.0	66.7	2	100.0	133.3	4	200.0	266.6	2	50.0	66.7
0101_100	50.0	66.7	2	100.0	133.3	4.5	225.0	300.0	2	50.0	66.7
0101_101	83.3	111.1	3	250.0	333.3	3.5	291.7	388.9	5	50.0	66.7
0101_110	83.3	111.1	3	250.0	333.3	4	333.3	444.4	5	50.0	66.7
0101_111	83.3	111.1	3	250.0	333.3	4.5	375.0	500.0	5	50.0	66.7
0110_000	60.0	80.0	2.5	150.0	200.0	2.5	150.0	200.0	3	50.0	66.7
0110_001	60.0	80.0	2.5	150.0	200.0	3	180.0	240.0	3	50.0	66.7
0110_010	60.0	80.0	2.5	150.0	200.0	3.5	210.0	280.0	3	50.0	66.7
0110_011	60.0	80.0	2.5	150.0	200.0	4	240.0	320.0	3	50.0	66.7
0110_100	60.0	80.0	2.5	150.0	200.0	4.5	270.0	360.0	3	50.0	66.7
0110_101	60.0	80.0	2.5	150.0	200.0	5	300.0	400.0	3	50.0	66.7
0110_110	60.0	80.0	2.5	150.0	200.0	6	360.0	480.0	3	50.0	66.7
0111_000	Reserved										
0111_001	50.0	66.7	3	150.0	200.0	3	150.0	200.0	3	50.0	66.7
0111_010	50.0	66.7	3	150.0	200.0	3.5	175.0	233.3	3	50.0	66.7
0111_011	50.0	66.7	3	150.0	200.0	4	200.0	266.6	3	50.0	66.7
0111_100	50.0	66.7	3	150.0	200.0	4.5	225.0	300.0	3	50.0	66.7
1000_000	Reserved										
1000_001	66.7	88.9	3	200.0	266.6	3	200.0	266.6	4	50.0	66.7

Table 18. Clock Configurations for PCI Host Mode (PCI_MODCK=1)^{1,2} (continued)

Mode ³	Bus Clock (MHz)		CPM Multiplication Factor ⁴	CPM Clock (MHz)		CPU Multiplication Factor ⁵	CPU Clock (MHz)		PCI Division Factor ⁶	PCI Clock (MHz)	
	Low	High		Low	High		Low	High		Low	High
0100_001	25.0	50.0	6	150.0	300.0	6	150.0	300.0	6	25.0	50.0
0100_010	25.0	50.0	6	150.0	300.0	7	175.0	350.0	6	25.0	50.0
0100_011	25.0	50.0	6	150.0	300.0	8	200.0	400.0	6	25.0	50.0
0101_000	60.0	100.0	2	120.0	200.0	2.5	150.0	250.0	4	30.0	50.0
0101_001	50.0	100.0	2	100.0	200.0	3	150.0	300.0	4	25.0	50.0
0101_010	50.0	100.0	2	100.0	200.0	3.5	175.0	350.0	4	25.0	50.0
0101_011	50.0	100.0	2	100.0	200.0	4	200.0	400.0	4	25.0	50.0
0101_100	50.0	100.0	2	100.0	200.0	4.5	225.0	450.0	4	25.0	50.0
0101_101	42.9	83.3	3	128.6	250.0	3.5	150.0	291.7	5	25.7	50.0
0101_110	41.7	83.3	3	125.0	250.0	4	166.7	333.3	5	25.0	50.0
0101_111	41.7	83.3	3	125.0	250.0	4.5	187.5	375.0	5	25.0	50.0
0110_000	60.0	120.0	2.5	150.0	300.0	2.5	150.0	300.0	6	25.0	50.0
0110_001	60.0	120.0	2.5	150.0	300.0	3	180.0	360.0	6	25.0	50.0
0110_010	60.0	120.0	2.5	150.0	300.0	3.5	210.0	420.0	6	25.0	50.0
0110_011	60.0	120.0	2.5	150.0	300.0	4	240.0	480.0	6	25.0	50.0
0110_100	60.0	120.0	2.5	150.0	300.0	4.5	270.0	540.0	6	25.0	50.0
0110_101	60.0	120.0	2.5	150.0	300.0	5	300.0	600.0	6	25.0	50.0
0110_110	60.0	120.0	2.5	150.0	300.0	6	360.0	720.0	6	25.0	50.0
0111_000	Reserved										
0111_001	50.0	100.0	3	150.0	300.0	3	150.0	300.0	6	25.0	50.0
0111_010	50.0	100.0	3	150.0	300.0	3.5	175.0	350.0	6	25.0	50.0
0111_011	50.0	100.0	3	150.0	300.0	4	200.0	400.0	6	25.0	50.0
0111_100	50.0	100.0	3	150.0	300.0	4.5	225.0	450.0	6	25.0	50.0
1000_000	Reserved										
1000_001	66.7	133.3	3	200.0	400.0	3	200.0	400.0	8	25.0	50.0

Table 18. Clock Configurations for PCI Host Mode (PCI_MODCK=1)^{1,2} (continued)

Mode ³	Bus Clock (MHz)		CPM Multiplication Factor ⁴	CPM Clock (MHz)		CPU Multiplication Factor ⁵	CPU Clock (MHz)		PCI Division Factor ⁶	PCI Clock (MHz)	
	Low	High		Low	High		Low	High		Low	High
1000_010	66.7	133.3	3	200.0	400.0	3.5	233.3	466.7	8	25.0	50.0
1000_011	66.7	133.3	3	200.0	400.0	4	266.7	533.3	8	25.0	50.0
1000_100	66.7	133.3	3	200.0	400.0	4.5	300.0	600.0	8	25.0	50.0
1000_101	66.7	133.3	3	200.0	400.0	6	400.0	800.0	8	25.0	50.0
1000_110	66.7	133.3	3	200.0	400.0	6.5	433.3	866.7	8	25.0	50.0
1001_000	Reserved										
1001_001	Reserved										
1001_010	57.1	114.3	3.5	200.0	400.0	3.5	200.0	400.0	8	25.0	50.0
1001_011	57.1	114.3	3.5	200.0	400.0	4	228.6	457.1	8	25.0	50.0
1001_100	57.1	114.3	3.5	200.0	400.0	4.5	257.1	514.3	8	25.0	50.0
1001_101	42.9	85.7	3.5	150.0	300.0	5	214.3	428.6	6	25.0	50.0
1001_110	42.9	85.7	3.5	150.0	300.0	5.5	235.7	471.4	6	25.0	50.0
1001_111	42.9	85.7	3.5	150.0	300.0	6	257.1	514.3	6	25.0	50.0
1010_000	75.0	150.0	2	150.0	300.0	2	150.0	300.0	6	25.0	50.0
1010_001	75.0	150.0	2	150.0	300.0	2.5	187.5	375.0	6	25.0	50.0
1010_010	75.0	150.0	2	150.0	300.0	3	225.0	450.0	6	25.0	50.0
1010_011	75.0	150.0	2	150.0	300.0	3.5	262.5	525.0	6	25.0	50.0
1010_100	75.0	150.0	2	150.0	300.0	4	300.0	600.0	6	25.0	50.0
1010_101	100.0	200.0	2	200.0	400.0	2.5	250.0	500.0	8	25.0	50.0
1010_110	100.0	200.0	2	200.0	400.0	3	300.0	600.0	8	25.0	50.0
1010_111	100.0	200.0	2	200.0	400.0	3.5	350.0	700.0	8	25.0	50.0
1011_000	Reserved										
1011_001	80.0	160.0	2.5	200.0	400.0	2.5	200.0	400.0	8	25.0	50.0
1011_010	80.0	160.0	2.5	200.0	400.0	3	240.0	480.0	8	25.0	50.0
1011_011	80.0	160.0	2.5	200.0	400.0	3.5	280.0	560.0	8	25.0	50.0
1011_100	80.0	160.0	2.5	200.0	400.0	4	320.0	640.0	8	25.0	50.0

- ⁶ CPM_CLK/PCI_CLK ratio. When PCI_MODCK = 1, the ratio of CPM_CLK/PCI_CLK should be calculated from PCIDF as follows:
- PCIDF = 3 > CPM_CLK/PCI_CLK = 4
 - PCIDF = 5 > CPM_CLK/PCI_CLK = 6
 - PCIDF = 7 > CPM_CLK/PCI_CLK = 8
 - PCIDF = 9 > CPM_CLK/PCI_CLK = 5
 - PCIDF = B > CPM_CLK/PCI_CLK = 6

7.2 PCI Agent Mode

These tables show configurations for PCI agent mode. The frequency values listed are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not exceed the frequency rating of the user's device. Note that in PCI agent mode the input clock is PCI clock.

Table 19. Clock Configurations for PCI Agent Mode (PCI_MODCK=0)^{1,2}

Mode ³	PCI Clock (MHz)		CPM Multiplication Factor ⁴	CPM Clock (MHz)		CPU Multiplication Factor ⁵	CPU Clock (MHz)		Bus Division Factor	Bus Clock (MHz)	
MODCK_H- MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
Default Modes (MODCK_H=0000)											
0000_000	60.0	66.7	2	120.0	133.3	2.5	150.0	166.7	2	60.0	66.7
0000_001	50.0	66.7	2	100.0	133.3	3	150.0	200.0	2	50.0	66.7
0000_010	50.0	66.7	3	150.0	200.0	3	150.0	200.0	3	50.0	66.7
0000_011	50.0	66.7	3	150.0	200.0	4	200.0	266.6	3	50.0	66.7
0000_100	50.0	66.7	3	150.0	200.0	3	180.0	240.0	2.5	60.0	80.0
0000_101	50.0	66.7	3	150.0	200.0	3.5	210.0	280.0	2.5	60.0	80.0
0000_110	50.0	66.7	4	200.0	266.6	3.5	233.3	311.1	3	66.7	88.9
0000_111	50.0	66.7	4	200.0	266.6	3	240.0	320.0	2.5	80.0	106.7
Full Configuration Modes											
0001_001	60.0	66.7	2	120.0	133.3	5	150.0	166.7	4	30.0	33.3
0001_010	50.0	66.7	2	100.0	133.3	6	150.0	200.0	4	25.0	33.3
0001_011	50.0	66.7	2	100.0	133.3	7	175.0	233.3	4	25.0	33.3
0001_100	50.0	66.7	2	100.0	133.3	8	200.0	266.6	4	25.0	33.3
0010_001	50.0	66.7	3	150.0	200.0	3	180.0	240.0	2.5	60.0	80.0
0010_010	50.0	66.7	3	150.0	200.0	3.5	210.0	280.0	2.5	60.0	80.0
0010_011	50.0	66.7	3	150.0	200.0	4	240.0	320.0	2.5	60.0	80.0
0010_100	50.0	66.7	3	150.0	200.0	4.5	270.0	360.0	2.5	60.0	80.0

Table 20. Clock Configurations for PCI Agent Mode (PCI_MODCK=1)^{1,2} (continued)

Mode ³	PCI Clock (MHz)		CPM Multiplication Factor ⁴	CPM Clock (MHz)		CPU Multiplication Factor ⁵	CPU Clock (MHz)		Bus Division Factor	Bus Clock (MHz)	
MODCK_H-MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
0100_100	25.0	50.0	6	150.0	300.0	4.5	225.0	450.0	3	50.0	100.0
0101_000	30.0	50.0	5	150.0	250.0	2.5	150.0	250.0	2.5	60.0	100.0
0101_001	25.0	50.0	5	125.0	250.0	3	150.0	300.0	2.5	50.0	100.0
0101_010	25.0	50.0	5	125.0	250.0	3.5	175.0	350.0	2.5	50.0	100.0
0101_011	25.0	50.0	5	125.0	250.0	4	200.0	400.0	2.5	50.0	100.0
0101_100	25.0	50.0	5	125.0	250.0	4.5	225.0	450.0	2.5	50.0	100.0
0101_101	25.0	50.0	5	125.0	250.0	5	250.0	500.0	2.5	50.0	100.0
0101_110	25.0	50.0	5	125.0	250.0	5.5	275.0	550.0	2.5	50.0	100.0
0110_000	Reserved										
0110_001	25.0	50.0	8	200.0	400.0	3	200.0	400.0	3	66.7	133.3
0110_010	25.0	50.0	8	200.0	400.0	3.5	233.3	466.7	3	66.7	133.3
0110_011	25.0	50.0	8	200.0	400.0	4	266.7	533.3	3	66.7	133.3
0110_100	25.0	50.0	8	200.0	400.0	4.5	300.0	600.0	3	66.7	133.3
0111_000	25.0	50.0	6	150.0	300.0	2	150.0	300.0	2	75.0	150.0
0111_001	25.0	50.0	6	150.0	300.0	2.5	187.5	375.0	2	75.0	150.0
0111_010	25.0	50.0	6	150.0	300.0	3	225.0	450.0	2	75.0	150.0
0111_011	25.0	50.0	6	150.0	300.0	3.5	262.5	525.0	2	75.0	150.0
1000_000	Reserved										
1000_001	25.0	50.0	6	150.0	300.0	2.5	150.0	300.0	2.5	60.0	120.0
1000_010	25.0	50.0	6	150.0	300.0	3	180.0	360.0	2.5	60.0	120.0
1000_011	25.0	50.0	6	150.0	300.0	3.5	210.0	420.0	2.5	60.0	120.0
1000_100	25.0	50.0	6	150.0	300.0	4	240.0	480.0	2.5	60.0	120.0
1000_101	25.0	50.0	6	150.0	300.0	4.5	270.0	540.0	2.5	60.0	120.0
1001_000	Reserved										
1001_001	Reserved										

Table 21. Pinout (continued)

Pin Name		Ball
MPC8272/MPC8248 and MPC8271/MPC8247	MPC8272/MPC8271 Only	
A30		B15
A31		A15
TT0		B3
TT1		E8
TT2		D7
TT3		C4
TT4		E7
$\overline{\text{TBST}}$		E3
TSIZ0		E4
TSIZ1		E5
TSIZ2		C3
TSIZ3		D5
$\overline{\text{ACK}}$		D3
$\overline{\text{ARTRY}}$		C2
$\overline{\text{DBG/IRQ7}}$		F16
$\overline{\text{DBB/IRQ3}}$		D18
D0		AC1
D1		AA1
D2		V3
D3		R5
D4		P4
D5		M4
D6		J4
D7		G1
D8		W6
D9		Y3
D10		V1
D11		N6
D12		P3
D13		M2
D14		J5

Table 21. Pinout (continued)

Pin Name		Ball
MPC8272/MPC8248 and MPC8271/MPC8247	MPC8272/MPC8271 Only	
D15		G3
D16		AB3
D17		Y1
D18		T4
D19		T3
D20		P2
D21		M1
D22		J1
D23		G4
D24		AB2
D25		W4
D26		V2
D27		T1
D28		N5
D29		L1
D30		H1
D31		G5
D32		W5
D33		W2
D34		T5
D35		T2
D36		N1
D37		K3
D38		H2
D39		F1
D40		AA2
D41		W1
D42		U3
D43		R2
D44		N2
D45		L2

Table 21. Pinout (continued)

Pin Name		Ball
MPC8272/MPC8248 and MPC8271/MPC8247	MPC8272/MPC8271 Only	
$\overline{CS2}$		AF5
$\overline{CS3}$		AC8
$\overline{CS4}$		AF6
$\overline{CS5}$		AD8
$\overline{CS6/BCTL1/SMI}$		AC9
$\overline{CS7/TLBISYNC}$		AB9
BADDR27/ $\overline{IRQ1}$		AB8
BADDR28/ $\overline{IRQ2}$		AC7
ALE/ $\overline{IRQ4}$		AF4
$\overline{BCTL0}$		AF3
$\overline{PWE0/PSDDQM0/PBS0}$		AD6
$\overline{PWE1/PSDDQM1/PBS1}$		AE5
$\overline{PWE2/PSDDQM2/PBS2}$		AE3
$\overline{PWE3/PSDDQM3/PBS3}$		AF2
$\overline{PWE4/PSDDQM4/PBS4}$		AC6
$\overline{PWE5/PSDDQM5/PBS5}$		AC5
$\overline{PWE6/PSDDQM6/PBS6}$		AD4
$\overline{PWE7/PSDDQM7/PBS7}$		AB5
PSDA10/PGPL0		AE2
$\overline{PSDWE/PGPL1}$		AD3
$\overline{POE/PSDRAS/PGPL2}$		AB4
$\overline{PSDCAS/PGPL3}$		AC3
$\overline{PGTA/PUPMWAIT/PGPL4}$		AD2
PSDAMUX/PGPL5		AC2
PCI_MODE ¹		AD22
PCI_CFG0 ($\overline{PCI_HOST_EN}$)		AC21
PCI_CFG1 ($\overline{PCI_ARB_EN}$)		AE22
PCI_CFG2 (DLL_ENABLE)		AE23
PCI_PAR		AF12
$\overline{PCI_FRAME}$		AD15
$\overline{PCI_TRDY}$		AF16

Table 21. Pinout (continued)

Pin Name		Ball
MPC8272/MPC8248 and MPC8271/MPC8247	MPC8272/MPC8271 Only	
PCI_AD16		AE16
PCI_AD17		AF17
PCI_AD18		AD16
PCI_AD19		AC16
PCI_AD20		AF18
PCI_AD21		AB16
PCI_AD22		AD17
PCI_AD23		AF19
PCI_AD24		AB17
PCI_AD25		AF20
PCI_AD26		AE19
PCI_AD27		AC18
PCI_AD28		AB18
PCI_AD29		AD19
PCI_AD30		AD21
PCI_AD31		AC20
PCI_C0/BE0		AE12
PCI_C1/BE1		AF13
PCI_C2/BE2		AC15
PCI_C3/BE3		AE18
IRQ0/NMI_OUT		A17
TRST ²		E21
TCK		B22
TMS		C23
TDI		B24
TDO		A22
TRIS		B23
PORESET ² /PCI_RST		C24
HRESET		D22
SRESET		F22
RSTCONF		A24

9 Package Description

This figure shows the side profile of the PBGA package to indicate the direction of the top surface view.

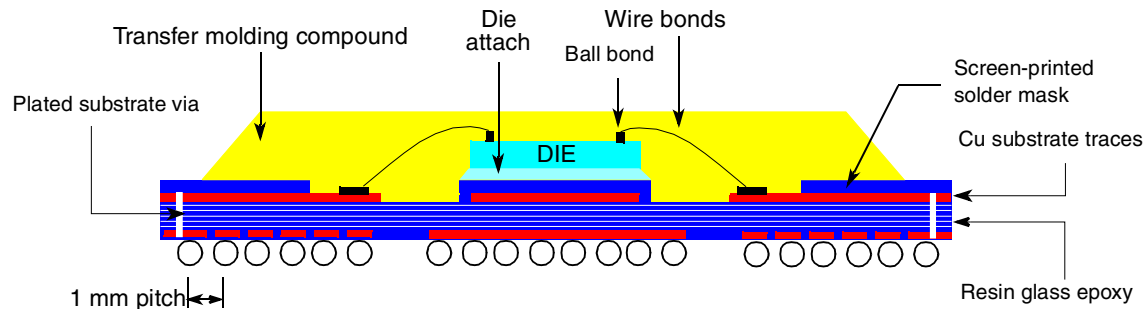


Figure 13. Side View of the PBGA Package Remove

9.1 Package Parameters

This table provides package parameters.

Table 22. Package Parameters

Code	Type	Outline (mm)	Interconnects	Pitch (mm)	Nominal Unmounted Height (mm)
VR, ZQ	PBGA	27 x 27	516	1	2.25

NOTE: Temperature Reflow for the VR Package

In the VR package, sphere composition is lead-free (see Table 2). This requires higher temperature reflow than what is required for other PowerQUICC II packages. Consult “Freescale PowerQUICC II Pb-Free Packaging Information” (MPC8250PBFREEPKG) available on www.freescale.com.

9.2 Mechanical Dimensions

This figure provides the mechanical dimensions and bottom surface nomenclature of the 516 PBGA package.

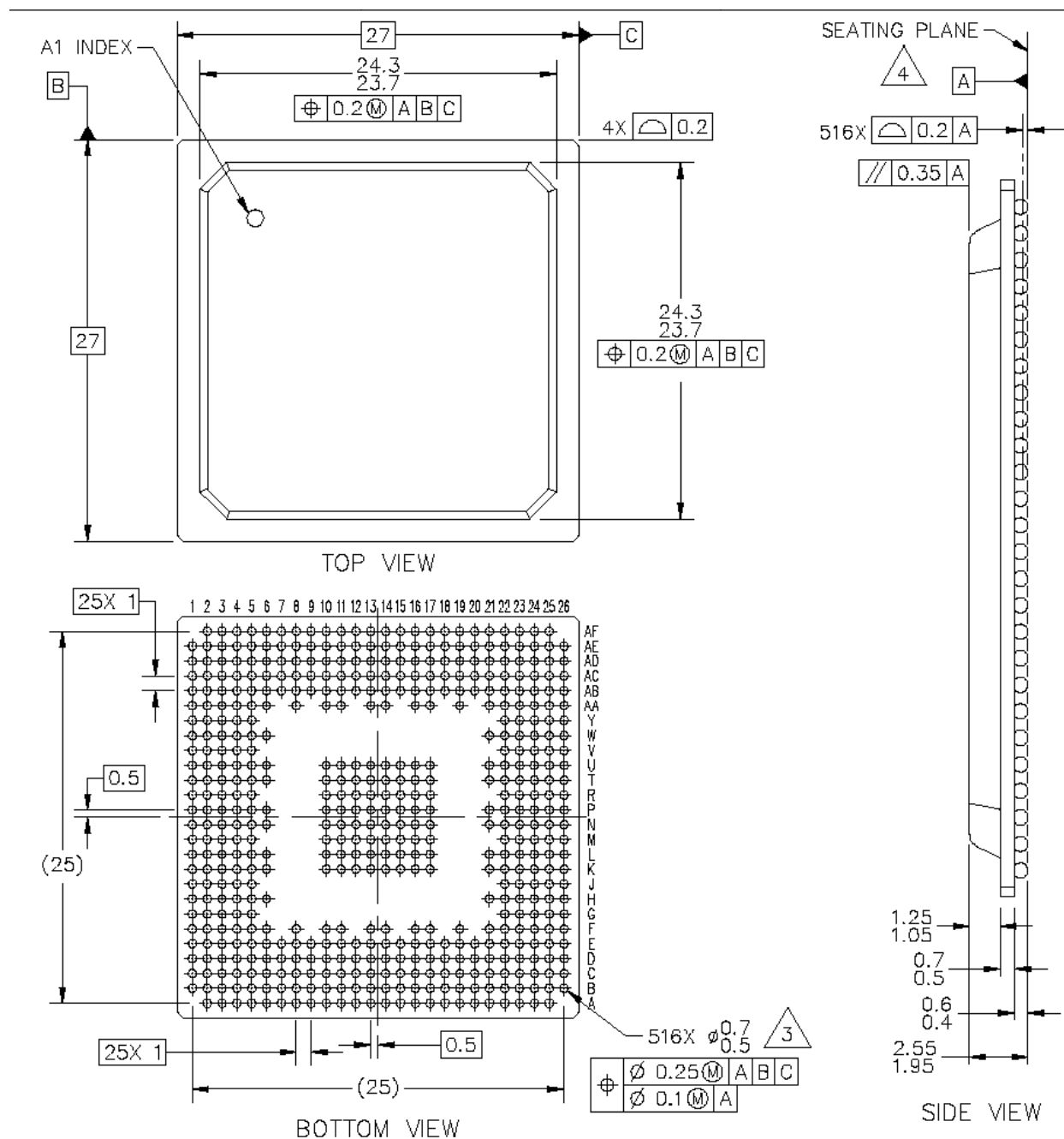


Figure 14. Mechanical Dimensions and Bottom Surface Nomenclature—516 PBGA

Table 23. Document Revision History (continued)

Revision	Date	Substantive Changes
1.2	09/2005	- Added 133-MHz to the list of frequencies in the opening sentence of Section 6, “AC Electrical Characteristics”. - Added 133 MHz columns to Table 9, Table 11, Table 12, and Table 13. - Added footnote 2 to Table 13. - Added the conditions note directly above Table 12.
1.1	01/2005	Modification for correct display of assertion level (“overbar”) for some signals
1.0	12/2004	- Section 1.1: Added 8:1 ratio to Internal CPM/bus clock multiplier values - Section 2: removed voltage tracking note Table 3: Note 2 updated regarding VDD/VCCSYN relationship to VDDH during power-on reset Table 4: Updated VDD and VCCSYN to 1.425 V - 1.575 V Table 8: Note 2 updated to reflect VIH=2.5 for TCK, TRST, PORESET; request for external pull-up removed. - Section 4.6: Updated description of layout practices Table 8: Note 3 added regarding IIC compatibility Table 8: Updated nominal and maximum power dissipation values Table 9: updated PCI impedance to 27Ω, updated 60x and MEMC values and added note to reflect configurable impedance - Section 6: Added sentence providing derating factor - Section 6.1: added Note: Rise/Fall Time on CPM Input Pins Table 9: updated values for following specs: sp36b, sp37a, sp38a, sp39a, sp38b, sp40, sp41, sp42, sp43, sp42a Table 11: updated values for following specs: sp16a, sp16b, sp18a, sp18b, sp20, sp21, sp22 - Section 6.2: added spread spectrum clocking note - Section 6.2: added CLKIN jitter note Table 12: combined specs sp11 and sp11a Table 13: sp30 Data Bus minimum delay values changed to 0.8 - Section 7: unit of ns added to Tval notes - Section 7: Updated all notes to reflect updated CPU Fmin of 150 MHz commercial temp devices, 175 MHz extended temp; CPM Fmin of 120 MHz. Section 7, “Clock Configuration Modes”: Updated all table footnotes reflect updated CPU Fmin of 150 MHz commercial temp devices, 175 MHz extended temp; CPM Fmin of 120 MHz. Table 21: correct superscript of footnote number after pin AD22 Table 21: remove DONE3 from PC12 Table 21: signals referring to TDMs C2 and D2 removed